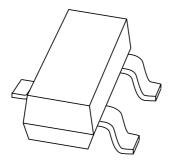
DISCRETE SEMICONDUCTORS

DATA SHEET



BAS17Low-voltage stabistor

Product data sheet Supersedes data of 1999 May 31 2003 Mar 25



NXP Semiconductors Product data sheet

Low-voltage stabistor

BAS17

FEATURES

• Low-voltage stabilization

• Forward voltage range: 580 to 960 mV

• Total power dissipation: max. 250 mW.

APPLICATIONS

• Low-voltage stabilization e.g.

- Bias stabilizer in class-B output stages

- Clipping

- Clamping

- Meter protection.

DESCRIPTION

Low-voltage stabilization diode in a small SOT23 plastic package.

MARKING

TYPE NUMBER	MARKING CODE(1)
BAS17	*A9

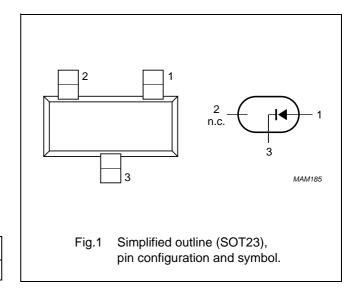
Note

1. * = p: Made in Hong Kong. * = t : Made in Malaysia.

* = W : Made in China.

PINNING

PIN	DESCRIPTION			
1	anode			
2	not connected			
3	cathode			



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _R	continuous reverse voltage		_	5	V
I _F	continuous forward current		_	200	mA
P _{tot}	total power dissipation	T _{amb} = 25 °C	_	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C

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ELECTRICAL CHARACTERISTICS

 $T_j = 25$ °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _F	forward voltage	see Fig.2				
		$I_F = 0.1 \text{ mA}$	580	_	660	mV
		I _F = 1 mA	665	_	745	mV
		$I_F = 5 \text{ mA}$	725	_	805	mV
		I _F = 10 mA	750	_	830	mV
		I _F = 100 mA	870	_	960	mV
I _R	reverse current	V _R = 4 V	_	_	5	μΑ
r _{dif}	differential resistance	$I_F = 0.5 \text{ mA}$	_	120	_	Ω
		I _F = 2 mA	_	80	_	Ω
S _F	temperature coefficient	I _F = 1 mA	_	-1.8	_	mV/K
C _d	diode capacitance	V _R = 0 V; f = 1 MHz	_	_	140	pF

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-tp}	thermal resistance from junction to tie-point		330	K/W
R _{th j-a}	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Device mounted on a FR4 printed-circuit board.

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GRAPHICAL DATA

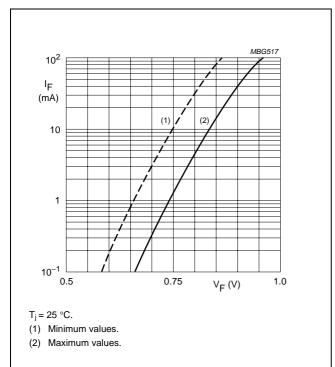


Fig.2 Forward current as a function of forward voltage

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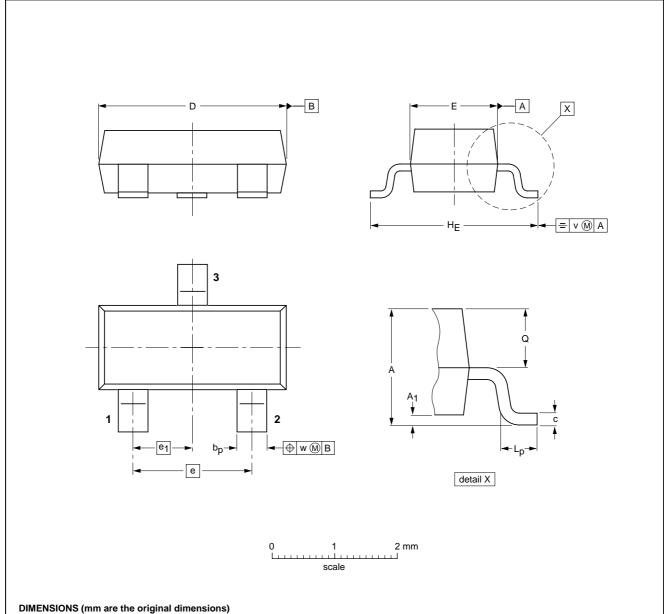
Low-voltage stabistor

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PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT23



DIMENSIONS (mm are	the original	dimensions)
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UN	IT	A	A ₁ max.	bp	C	D	E	е	e ₁	HE	L _p	Q	٧	w
mı	n	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC EIAJ PROJECTION		ISSUE DATE		
SOT23		TO-236AB				-97-02-28 99-09-13

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Low-voltage stabistor

BAS17

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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- 2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors. No changes were made to the content, except for the legal definitions and disclaimers.

Contact information

For additional information please visit: http://www.nxp.com

For sales offices addresses send e-mail to: salesaddresses@nxp.com

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401 Building No.5, JiuGe Business Center, Lane 2301, Yishan Rd Minhang District, Shanghai , China

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Email amall@ameya360.com

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Skype ameyasales1 ameyasales2

Customer Service :

Email service@ameya360.com

Partnership :

Tel +86 (21) 64016692-8333

Email mkt@ameya360.com